l≪ypton	
S/N:	

KTY PION SOLUTIONS	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION:  LAYER 12 - SILKSCREEN BOTTOM		

	DONGLE * SP31
3P3V TEST	3527 150 3537
J2 RST TP1 J1	119 22 23 23 23 23 23 24 24 24 24 24 24 24 24 24 24 24 24 24
GND MODE 22	175 —   176 —
	** **10 — 0 ** 0 ** 0 ** 0 ** 0 ** 0 **

KTY PION SOLUTIONS	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION:  LAYER 11 - SILKSCREEN TOP		

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